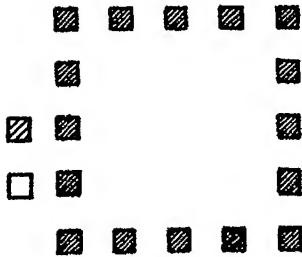


HIGH DENSITY INTEGRATED CIRCUITS AND THE METHOD
OF PACKAGING THE SAME

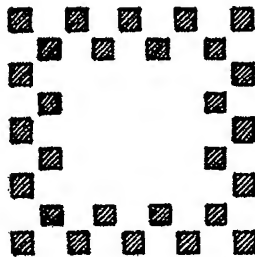
Inventor: Daniel Wang

Docket No. 669-77 CON



PRIOR ART

Fig. 1.
PERIMETER I/O



PRIOR ART

Fig. 2.
STAGGERED PERIMETER I/O

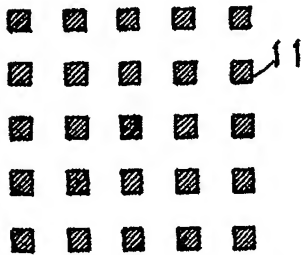


Fig. 3.
FULL ARRAY

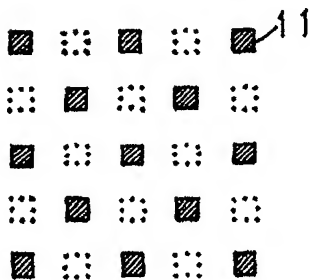


Fig. 4.
DEPOPULATED ARRAY

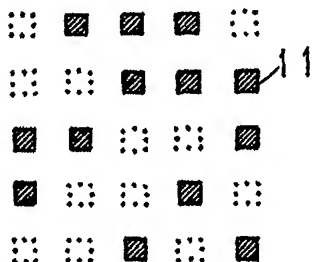


Fig. 5.
RANDOM ARRAY

4005744B, 012502

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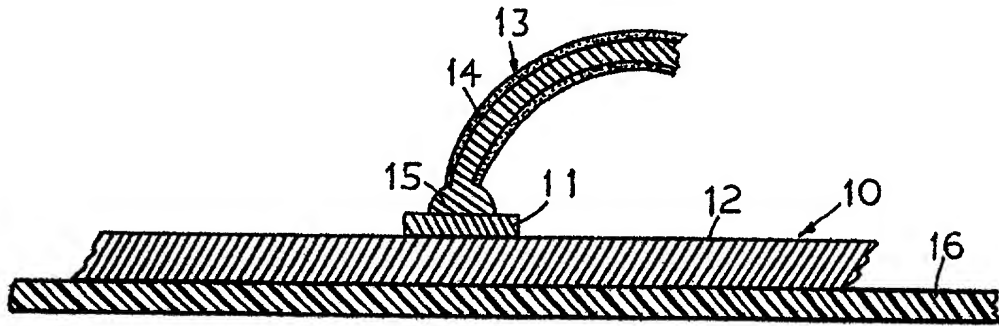


Fig. 6.

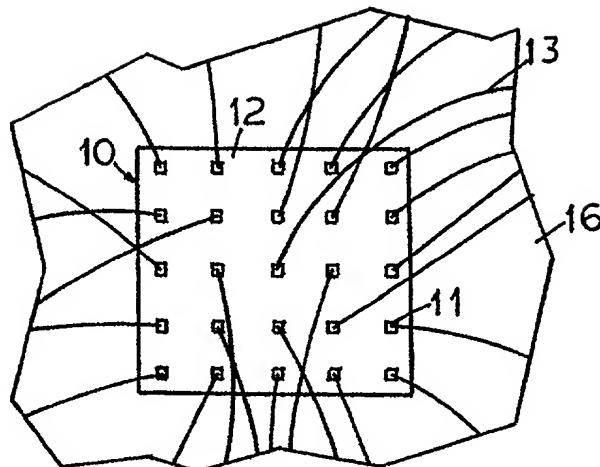


Fig. 7.

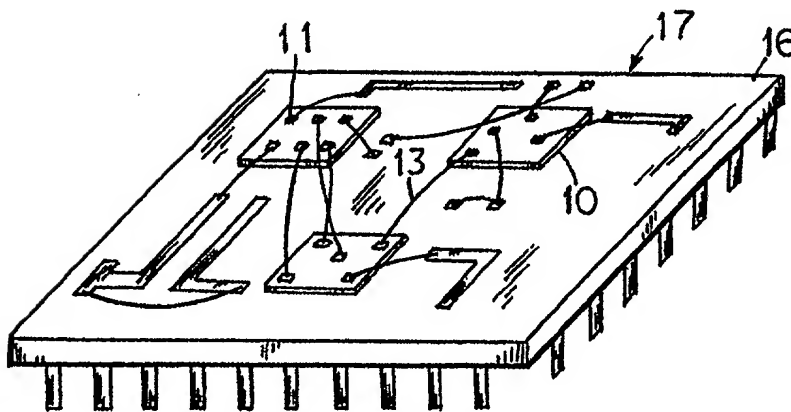


Fig. 8.